



Type	Part Number	Density	Voltage	Speed(MHz/CLK)	Temp. Range	PKG Type	Sample	MOQ				
								TRAY	Tape&Reel(R)	Tube (T)		
SPI NOR	FM25M64C-1AIB1	64Mb	1.8V	104MHz	-40°C~85°C	8 pin 208mil SOIC	Y		2000	9200		
	8 contact 6x5 WSON					Y		3000				
	8 pin VSOP					N		3000				
	WLCSP					Y		3000				
	KGD											
	8 pin 208mil SOIC					Dev						
	8 contact 6x5 WSON					Dev						
	8 contact 3x4 USON					Dev						
	WLCSP					Y		3000				
	FM25M64C-1AIB4	128Mb		104MHz		8 pin 208mil SOIC	Y		2000	9200		
	8 contact 6x5 WSON					Y		3000				
	8 pin VSOP					N		3000				
	WLCSP					Y		4000				
	KGD											
	WLCSP					Y		4000				
	8 pin 208mil SOIC					Y	3850					
	8 contact 6x5 WSON					Y	5700					
	WLCSP					Y		3000				
	FM25M64C-1AIB7	256Mb		104MHz		KGD						
	8 pin 208mil SOIC					Y	3850					
	8 contact 6x5 WSON					Y	5700					
	WLCSP					Y						
	KGD											
	DS25M64E-1AIB1					512Mb	133MHz	-40°C~105°C	16 pin 300mil SOP	Dev		
DS25M64E-1AIB4	1Gb		133MHz		-40°C~105°C				16 pin 300mil SOP	Dev		
DS25M64E-1AIBN												
FM25M64C-13IBP												
FM25M4AA-1AIB1												
FM25M4AA-1AIB4												
FM25M4AA-1AIB7												
FM25M4AA-1AIBP												
FM25M4AA-1AIBW												
FM25M4AA-13IBP												
DS25M4AB-1AIB1												
DS25M4AB-1AIB4												
DS25M4AB-1AIBP												
DS25M4AB-1AIBW												
DS25M4BA-1AIB1												
DS25M4BA-1AIB4												
DS25M4BA-1AIBP												
DS25M4BA-1AIBW												

Type	Part Number	Density	Voltage	Speed(MHz/CLK)	Temp. Range	PKG Type	Sample	MOQ	
								TRAY	Tape&Reel(R)
DDR3	FM38D08SAA-8KFD	1Gb	1.5V	800MHz	0℃~95℃	FBGA 78(7.5*11*1.2mm)	N		
	FM38D16SAB-8KFD		1.5V	800MHz		FBGA 96(7.5*13*1.2mm)	Y	1600	
	FM38D16SAB-8KGD		1.35V/1.5V	800MHz		FBGA 96(7.5*13*1.2mm)	N		
	DS38E16SBB-8KFB	2Gb	1.5V	800MHz	-40℃~95℃	FBGA 96(7.5*13*1.2mm)	N	1600	
	DS38E16SBB-9MFB		1.5V	933MHz		WBGA 96(7.5*13*1.2mm)	Y	1600	
	DS38E16SBB-9MGB		1.35V/1.5V			WBGA 96(7.5*13*1.2mm)	Y	1600	
	FM38E16SAB-9MGD		1.35V/1.5V			FBGA 96(7.5*13.5*1.2mm)	Y	2090	
	FM38F16SAD-8KGD	4Gb	1.35V/1.5V	800MHz	0℃~95℃	FBGA 96(9*13.5*1.2mm)	N	1800	
	FM38F16SAD-9MFD		1.5V	933MHz		FBGA 96(9*13.5*1.2mm)	Y	1800	
	FM38F16SBB-8KGD		1.35V/1.5V	800MHz		FBGA 96(7.5*13.5*1.2mm)	N	2090	
	FM38F16SBB-9MGD		1.35V/1.5V	933MHz		FBGA 96(7.5*13.5*1.2mm)	Y	2090	
	DS38F16SMB-9MFB		1.5V	933MHz		-40℃~95℃	WBGA 96(7.5*13*1.2mm)	Dev	1600
	LPDDR4X	DSF2G32VMA-4ADI	2Gb	1.1V	2133MHz	-40℃~85℃	FBGA 200Ball	Dev	

Type	Part Number	NAND			DRAM				Temp. Range	PKG Type	Sample	MOQ/TRAY
		Density	Org	Voltage	Density	Org	Type	Speed				
MCP	FMN1SD5SBB-50IA	1Gb	x16	1.8V	512Mb	x16	LPDDR1	200MHz	-40℃~85℃	FBGA 130(8x9x1.0mm)	N	1600
	FMN1ET1TCB-25IH	1Gb	x8	1.8V	1Gb	x32	LPDDR2	400MHz		FBGA 162(8x10.5x1.0mm)	Y	1360
	FMN2ET1TCD-25IH	2Gb	x8	1.8V	1Gb	x32	LPDDR2	400MHz		FBGA 162(8x10.5x1.0mm)	Y	1360
	FMN2ET2SCD-25IH	2Gb	x8	1.8V	2Gb	X16	LPDDR2	400MHz		FBGA 162(8x10.5x1.0mm)	Y	1360
	FMN2ET2TCD-25IH	2Gb	x8	1.8V	2Gb	X32	LPDDR2	400MHz		FBGA 162(8x10.5x1.0mm)	Y	1360
	FMN4ET2TCB-25IH	4Gb	x8	1.8V	2Gb	x32	LPDDR2	400MHz		FBGA 162(8x10.5x1.0mm)	Y	1360
	FMN4ET4DCF-25IH	4Gb	x8	1.8V	4Gb	x32	LPDDR2	400MHz		FBGA 162(8x10.5x1.1mm)	Y	1360

Type	Part Number	Density	Voltage	Speed(MHz/CLK)	Temp. Range	PKG Type	Sample	MOQ		
								TRAY	Tape&Reel(R)	Tube (T)
PPI NAND	FMND1G08U3D-JA	1Gb	3.3V	25ns	-40℃~105℃	TSOP 48(12*20mm)	Y	960	2000	
	FMND4G08S3B-A2D	4Gb	1.8V	45ns		VFBGA 63(9*11mm)	Y	2100		
	FMND4G08U3F-A2D	4Gb	3.3V	25ns		VFBGA 63(9*11mm)	Y	2100		
	DSND8G08S3M-JD	8Gb	1.8V	45ns		VFBGA 63(9*11mm)	N	2100		
SPI NAND	DS35Q1GA-A2B	1Gb	3.3V	104Mhz	-40℃~125℃	WSON 8x6	Y	3840		
	DS35M2GA-JB	2Gb	1.8V	104Mhz		WSON 8x6	Y	3840		
	DS35Q2GA-JB	2Gb	3.3V	104Mhz		WSON 8x6	Y	3840		
	DS35Q2GA-A2B					WSON 8x6	Y	3840		
	DS35Q2GA-A2E					BGA 24(5X5-1)	Y			
SPI NOR	DS25M4AB-1AA1B8	128Mb	1.8V	104Mhz	-40℃~125℃	BGA24	Dev			
PPI NOR	DS29S01GBBx-11I0	1Gb	3.3V	110ns	-40℃~85℃	56pin-TSOP	Dev			
	DS29S01GBBx-11I1					64-Ball LBGA	Dev			

High reliability:

PS: DS35Q1GA-A2B, DS35Q2GA-A2E, FMND4G08S3B-A2D & FMND4G08U3F-A2D support automotive AEC-Q100 grade2(ES sample without AEC-Q100 full qualification now), DS35Q2GA-A2B supports automotive AEC-Q100 grade2(with AEC-Q100 full qualification)

DS25M4AB-1AA1B8 supports automotive AEC-Q100 grade1(with AEC-Q100 full qualification and prepare CS sample now)

注:

- 1, 表中 Sample 状态不分库位及 ES 和 CS, Dev 表示开发中。因个别 sample 会因样片库临时用完或补样片偶有变化, 请以当时情况为准, 申请样片若有特殊需求或是不清楚的请沟通 check。
- 2, Part Number 列的料号, 不包含包装形式, 客户下单时需要根据具体的包装形式在该料号后加上包装位(参见最后一列 MOQ, Tape&Reel 加 R, Tube 加 T, Tray 的默认不加, 比如 DS35M1GA-IB 为 tray, DS35M1GA-IBR 为 Tape&Reel)。表里列出 MOQ 的是我们做过的包装形式, 大多数也是主流在出货的(但 Tube 的目前基本没怎么出), 所以请销售在客户下单前先和销售助理确认是否有该包装的货。若客户必须要我们暂未做过的包装, 可反馈来评估。